ON Semiconductor

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www.onsemi.com

SMDA05-6R2

Unidirectional TVS Array for High-Speed Data Line Protection

The SMDA05−6R2 transient voltage suppressor is designed to protect equipment attached to up to six high speed communication lines from ESD, EFT, and lightning.

Features:

- SO−8 Package
- Peak Power − 400 Watts 8 x 20 μS
- ESD Rating:
  IEC 61000−4−2 (ESD) 15 kV (air) 8 kV (contact)
  IEC 61000−4−4 (EFT) 40 A (5/50 ns)
  IEC 61000−4−5 (lightning) 12 (8/20 μs)
- UL Flammability Rating of 94 V−0

Typical Applications:

- High Speed Communication Line Protection
- 5.0 V Data and I/O Lines
- Microprocessor Based Equipment
- LAN/WAN Equipment
- Servers
- Notebook and Desktop PC
- Instrumentation
- Peripherals

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Power Dissipation 8 x 20 μs @ T_A = 25°C (Note 1)	P_{pk}	400	W
Peak Pulse Current 8 x 20 μs @ T_A = 25°C (Note 1)	I_{PP}	17	A
Junction and Storage Temperature Range	T_J, T_{stg}	−55 to +150	°C
Lead Solder Temperature − Maximum 10 Seconds Duration	T_L	260	°C

1. Non−repetitive current pulse 8 x 20 μS exponential decay waveform

ON Semiconductor®

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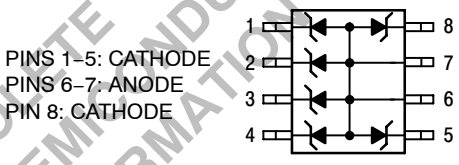
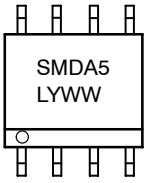
SO−8
VOLTAGE SUPPRESSOR
300 WATTS PEAK POWER
6 VOLTS

PIN CONFIGURATION AND SCHEMATIC



SO−8
CASE 751
PLASTIC

MARKING DIAGRAM



SMDA5 = Device Code
L = Location Code
Y = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping†
SMDA05−6R2	SO−8	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage @ I_t = 1.0 mA	V_{BR}	6.0	–	–	V
Reverse Leakage Current @ V_{RWM} = 5.0 Volts	I_R	N/A	–	20	μA
Maximum Clamping Voltage @ I_{PP} = 1.0 A, 8 x 20 μS	V_C	N/A	–	9.8	V
Maximum Clamping Voltage @ I_{PP} = 5.0 A, 8 x 20 μS	V_C	N/A	–	11	V
Maximum Peak Pulse Current	I_{PP}	–	–	17	A

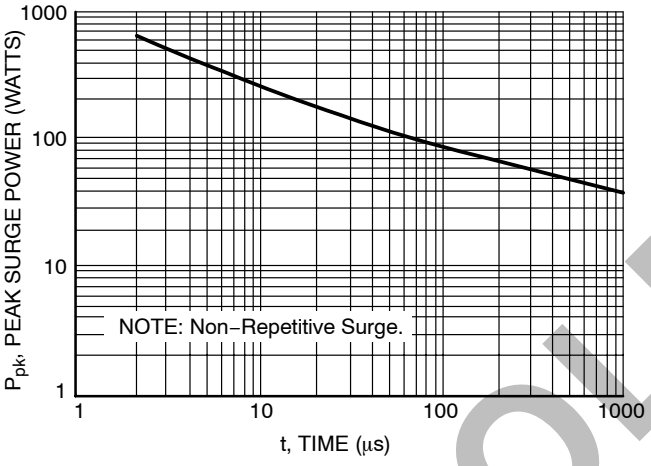


Figure 1. Pulse Width

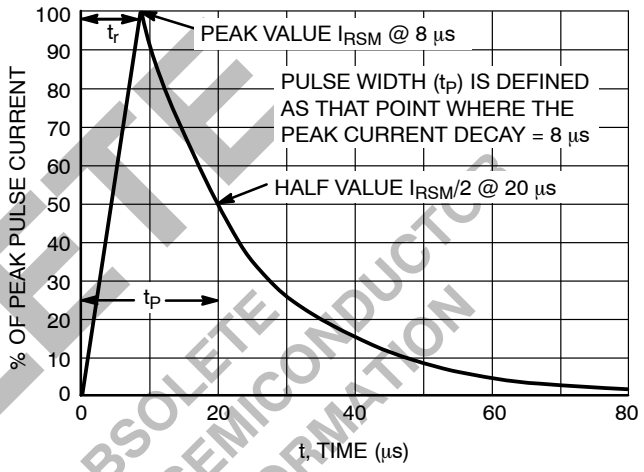
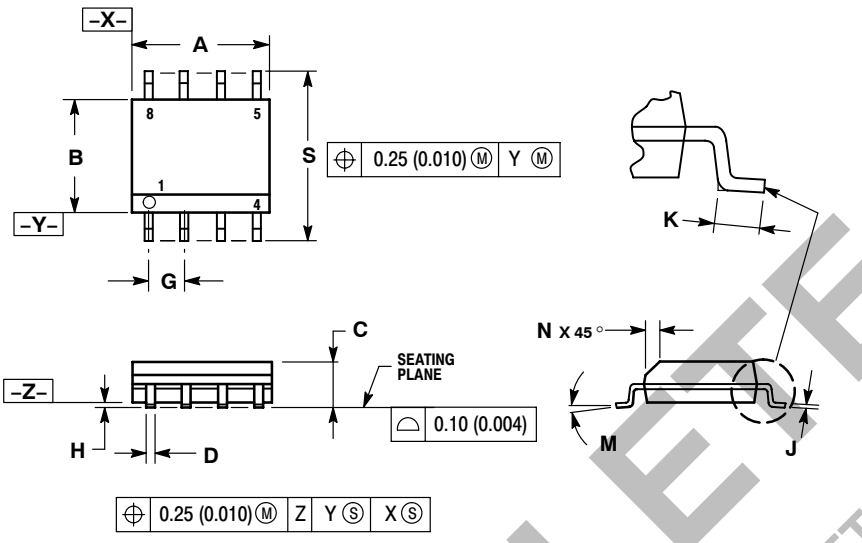


Figure 2. 8 × 20 μs Pulse Waveform

PACKAGE DIMENSIONS

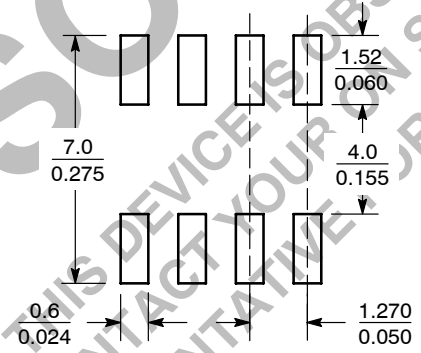
SO−8
CASE 751−07
ISSUE AB



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDAARD IS 751−07

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*



SCALE 6:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
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Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center
2−9−1 Kamimeguro, Meguro−ku, Tokyo, Japan 153−0051
Phone: 81−3−5773−3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

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